TPS79401, TPS79418





# ULTRALOW-NOISE, HIGH PSRR, FAST RF 250-mA LOW-DROPOUT LINEAR REGULATORS

#### **FEATURES**

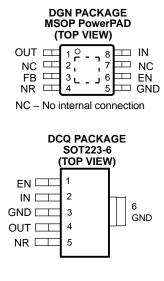
- 250-mA Low-Dropout Regulator With Enable
- Available in 1.8 V, 2.5 V, 2.8 V, 3 V, 3.3 V, and Adjustable (1.2 V to 5.5 V)
- High PSRR (60 dB at 10 kHz)
- Ultralow Noise (32 μVrms, TPS79428)
- Fast Start-Up Time (50 μs)
- Stable With a 2.2-µF Ceramic Capacitor
- Excellent Load/Line Transient Response
- Very Low Dropout Voltage (155 mV at Full Load)
- Available in MSOP-8 and SOT223-6 Packages

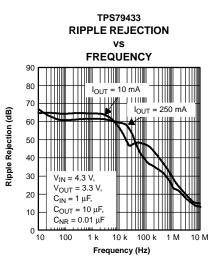
#### **APPLICATIONS**

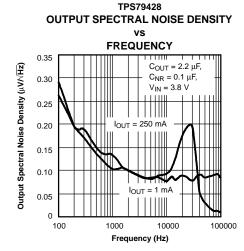
- RF: VCOs, Receivers, ADCs
- Audio
- Bluetooth™. Wireless LAN
- Cellular and Cordless Telephones
- Handheld Organizers, PDAs

#### **DESCRIPTION**

The TPS794xx family of low-dropout (LDO) linear voltage regulators features high power-supply rejection ratio (PSRR), ultralow-noise, fast start-up, and excellent line and load transient responses in small outline, MSOP-8 PowerPAD™ and SOT223-6 packages. Each device in the family is stable with a small 2.2-uF ceramic capacitor on the output. The family uses an advanced, proprietary BiCMOS fabrication process to yield extremely low dropout voltages (e.g., 155 mV at 250 mA). Each device achieves fast start-up times (approximately 50 µs with a 0.001-µF bypass capacitor) while consuming low quiescent current (170 µA typical). Moreover, when the device is placed in standby mode, the supply current is reduced to less than 1 µA. The TPS79428 exhibits approximately 32 µV<sub>RMS</sub> of output voltage noise at 2.8 V output with a 0.1-µF bypass capacitor. Applianalog components cations with that noise-sensitive, such as portable RF electronics, benefit from the high PSRR and low noise features as well as the fast response time.







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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

#### **ORDERING INFORMATION**

PRODUCT	VOLTAGE	PACKAGE	TJ	SYMBOL	PART NUMBER	TRANSPORT MEDIA, QUANTITY
	Adjustable	MSOP-8		AXL	TPS79401DGNR	Tape and Reel, 2500
TPS79401					TPS79401DGNT	Tape and Reel, 250
17379401		SOT223-6		PS79401	TPS79401DCQR	Tape and Reel, 2500
		501223-6			TPS79401DCQ	Tube, 78
		MSOP-8		AXM	TPS79418DGNR	Tape and Reel, 2500
TPS79418	1.8 V	WISOF-6		AAIVI	TPS79418DGNT	Tape and Reel, 250
173/9410	1.0 V	SOT223-6		PS79418	TPS79418DCQR	Tape and Reel, 2500
		301223-6		P3/9410	TPS79418DCQ	Tube, 78
TPS79423	2.5 V	MSOP-8	=	AYB	TPS79425DGNR	Tape and Reel, 2500
					TPS79425DGNT	Tape and Reel, 250
		SOT223-6	-40°C to 125°C	PS79425	TPS79425DCQR	Tape and Reel, 2500
		301223-0			TPS79425DCQ	Tube, 78
	2.8 V	MSOP-8		AYC	TPS79428DGNR	Tape and Reel, 2500
TPS79428					TPS79428DGNT	Tape and Reel, 250
17379420		2.0 v	SOT223-6	PS79428	DC70420	TPS79428DCQR
		501223-6		P3/9426	TPS79428DCQ	Tube, 78
	3 V	MSOP-8		AYD	TPS79430DGNR	Tape and Reel, 2500
TPS79430		WISOF-6			TPS79430DGNT	Tape and Reel, 250
17379430		SOT223-6		PS79430	TPS79430DCQR	Tape and Reel, 2500
				P579430	TPS79430DCQ	Tube, 78
	2.2.1/	MSOP-8		AYE	TPS79433DGNR	Tape and Reel, 2500
TPS79433					TPS79433DGNT	Tape and Reel, 250
173/9433	3.3 V	SOT223-6		PS79433	TPS79433DCQR	Tape and Reel, 2500
					TPS79433DCQ	Tube, 78



#### **ABSOLUTE MAXIMUM RATINGS**

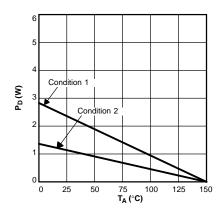
over operating temperature range unless otherwise noted(1)

	VALUE
V <sub>IN</sub> range	-0.3 V to 6 V
V <sub>EN</sub> range	-0.3 V to V <sub>IN</sub> + 0.3 V
V <sub>OUT</sub> range	-0.3 V to 6 V
Peak output current	Internally limited
ESD rating, HBM	2 kV
ESD rating, CDM	500 V
Continuous total power dissipation	See Dissipation Ratings Table
Junction temperature range, T <sub>J</sub>	-40°C to 150°C
Storage temperature range, T <sub>stg</sub>	-65°C to 150°C

<sup>(1)</sup> Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### **PACKAGE DISSIPATION RATINGS**

PACKAGE	AIR FLOW (CFM)	R <sub>θ</sub> JC(°C/W)	R <sub>θJA</sub> (°C/W)	$T_A \le 25^{\circ}C$ POWER RATING	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 85°C POWER RATING
	0	8.47	55.09	2.27 W	1.45 W	1.18 W
DGN	150	8.21	49.97	2.50 W	1.60 W	1.30 W
	250	8.20	48.10	2.60 W	1.66 W	1.35 W



CONDITIONS	PACKAGE	PCB AREA	θ <b>JA</b>
1	SOT223	4in <sup>2</sup> Top Side Only	53°C/W
2	SOT223	0.5in <sup>2</sup> Top Side Only	110°C/W

Figure 1. SOT223 Power Dissipation



## **ELECTRICAL CHARACTERISTICS**

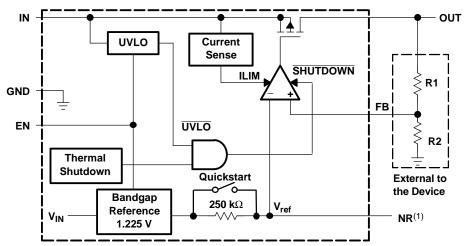
Over recommended operating temperature range (T<sub>J</sub> = -40°C to 125°C),  $V_{EN} = V_{IN}, V_{IN} = V_{OUT(nom)} + 1 V^{(1)}, I_{OUT} = 1 mA, C_{OUT} = 10 \mu F, C_{NR} = 0.01 \mu F$ , unless otherwise noted. Typical values are at 25°C.

	PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT		
V <sub>IN</sub>	Input voltage <sup>(1)</sup>				2.7		5.5	V		
I <sub>OUT</sub>	Continuous output curren	t			0		250	mA		
$V_{FB}$	Internal reference	TPS79401	$T_J = 25^{\circ}C$		1.220	1.225	1.230	V		
V <sub>OUT</sub>	Output voltage range	TPS79401			$V_{FB}$		5.5 - V <sub>DO</sub>	V		
	Accuracy <sup>(1)</sup>		$V_{OUT} + 1 \ V \le V_{IN} \le 5.5 \ V$	$0 \text{ mA} \le I_{OUT} \le 250 \text{ mA}$	-3.0		+3.0	%		
	Output voltage line regula $(\Delta V_{OUT}\%/\Delta V_{IN})^{(1)}$	ation	V <sub>OUT</sub> + 1 V < V <sub>IN</sub> ≤ 5.5 V			0.05	0.12	%/V		
	Load regulation (ΔV <sub>OUT</sub> %	/ΔI <sub>OUT</sub> )	0 μA < I <sub>OUT</sub> < 250 mA			10		mV		
	- (0)	TPS79428	I <sub>OUT</sub> = 250 mA			155	210			
	Dropout voltage <sup>(2)</sup> V <sub>IN</sub> = V <sub>OUT(nom)</sub> - 0.1 V	TPS79430	I <sub>OUT</sub> = 250 mA			155	210	mV		
	VIN — VOUT(nom) O.1 V	TPS79433	I <sub>OUT</sub> = 250 mA			145	200	0		
	$ \begin{array}{llllllllllllllllllllllllllllllllllll$				925		mA			
			0 μA < I <sub>OUT</sub> < 250 mA			170	220	μΑ		
			V <sub>EN</sub> = 0 V	2.7 V < V <sub>IN</sub> < 5.5 V		0.07	1	μΑ		
			V <sub>FB</sub> = 1.8 V				1	μΑ		
		TPS79428	f = 100 Hz	I <sub>OUT</sub> = 250 mA		65				
	Power-supply ripple rejection		f = 10 kHz	I <sub>OUT</sub> = 250 mA		60		dB		
	10,000.011		f = 100 kHz	I <sub>OUT</sub> = 250 mA		40				
				C <sub>NR</sub> = 0.001 µF		55				
	Output poice voltage (TD)	C70420\	BW = 100 Hz to 100 kHz, I <sub>OUT</sub> = 250 mA	$C_{NR} = 0.0047 \ \mu F$		36		μV <sub>RMS</sub>		
	Output noise voltage (TP:	379420)		$C_{NR} = 0.01 \ \mu F$		33				
				$C_{NR} = 0.1 \mu F$		32				
				C <sub>NR</sub> = 0.001 µF		50		μs		
	Time, start-up (TPS79428	3)	$R_L$ - 14 $\Omega$ , $C_{OUT}$ = 1 $\mu F$	$C_{NR} = 0.0047  \mu F$		70				
				C <sub>NR</sub> = 0.01 μF		100				
	High-level enable input voltage  Low-level enable input voltage		2.7 V < V <sub>IN</sub> < 5.5 V		1.7		V <sub>IN</sub>	V		
			2.7 V < V <sub>IN</sub> < 5.5 V		0		0.7	V		
	EN pin current		V <sub>EN</sub> = 0		1		1	μΑ		
	UVLO threshold		V <sub>CC</sub> rising		2.25		2.65	V		
	UVLO hysteresis					100		mV		

 <sup>(1)</sup> Minimum V<sub>IN</sub> is 2.7 V or V<sub>OUT</sub> + V<sub>DO</sub>, whichever is greater.
 (2) Dropout is not measured for the TPS79418 and TPS79425 since minimum V<sub>IN</sub> = 2.7 V.
 (3) For adjustable versions, this applies only after V<sub>IN</sub> is applied; then V<sub>EN</sub> transitions high to low.

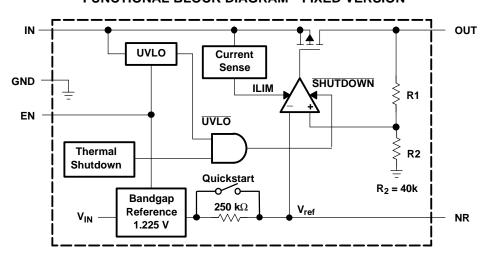


#### FUNCTIONAL BLOCK DIAGRAM—ADJUSTABLE VERSION



(1) Not Available on DCQ (SOT223) options.

#### FUNCTIONAL BLOCK DIAGRAM—FIXED VERSION

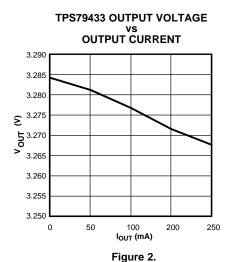


## **Terminal Functions**

TERMINAL						
NAME	DGN (MSOP)	DCQ (SOT223)	DESCRIPTION			
NR	4	5	Connecting an external capacitor to this pin bypasses noise generated by the internal bandgap. This improves power-supply rejection and reduces output noise.			
EN	6	1	The EN terminal is an input which enables or shuts down the device. When EN goes to a logic high, the device will be enabled. When the device goes to a logic low, the device is in shutdown mode.			
FB	3	5	This terminal is the feedback input voltage for the adjustable device.			
GND	5, PAD	3	Regulator ground.			
IN	8	2	Unregulated input to the device.			
NC	2, 7		No internal connection.			
OUT	1	4	Output of the regulator.			



#### TYPICAL CHARACTERISTICS



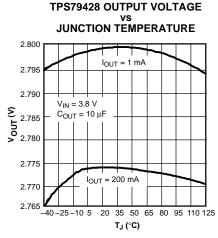
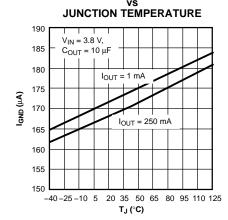


Figure 3.

**TPS79428 OUTPUT SPECTRAL** 

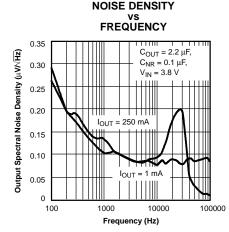


**TPS79428 GROUND CURRENT** 

Figure 4.

TPS79428 OUTPUT SPECTRAL

**NOISE DENSITY** 



**TPS79428 OUTPUT SPECTRAL** 

Figure 5.

**TPS79428 ROOT MEAN SQUARED** 

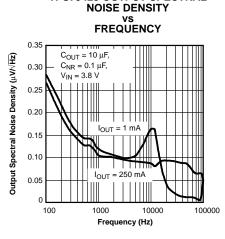


Figure 6.

**TPS79433 OUTPUT IMPEDANCE** 

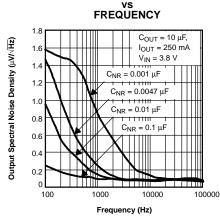


Figure 7.

**TPS79428 DROPOUT VOLTAGE** 

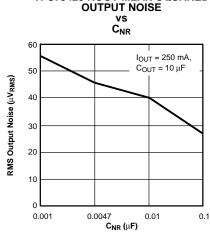


Figure 8.

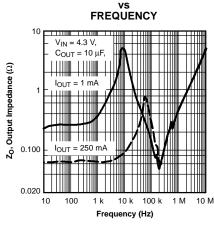


Figure 9.

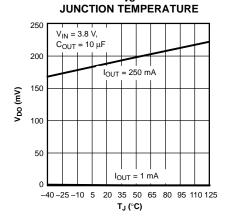
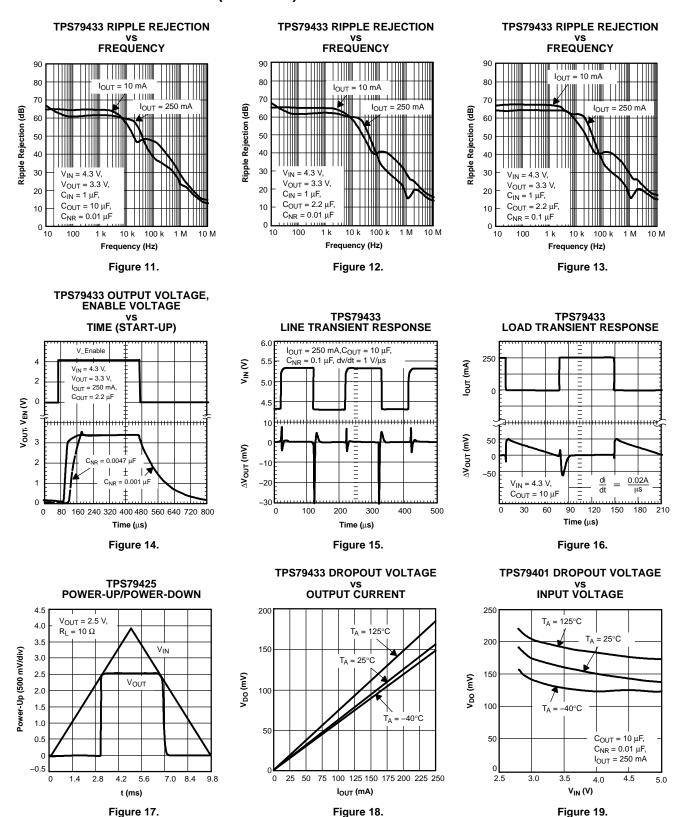


Figure 10.



#### **TYPICAL CHARACTERISTICS (continued)**





### **TYPICAL CHARACTERISTICS (continued)**

#### TPS79428 TYPICAL REGIONS OF STABILITY EQUIVALENT SERIES RESISTANCE (ESR) vs OUTPUT CURRENT

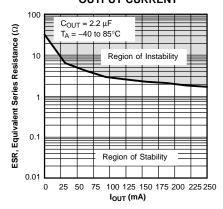


Figure 20.

#### TPS79428 TYPICAL REGIONS OF STABILITY EQUIVALENT SERIES RESISTANCE (ESR) VS OUTPUT CURRENT

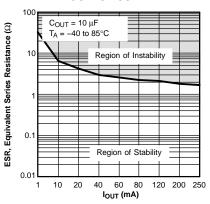


Figure 21.



#### **APPLICATION INFORMATION**

The TPS794xx family of low-dropout (LDO) regulators has been optimized for use in noise-sensitive equipment. The device features extremely low dropout voltages, high PSRR, ultralow output noise, low quiescent current, and enable input to reduce supply currents to less than 1  $\mu$ A when the regulator is turned off.

A typical application circuit is shown in Figure 22.

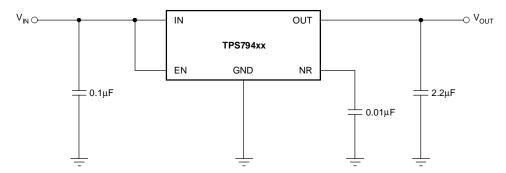


Figure 22. Typical Application Circuit

#### **External Capacitor Requirements**

A 0.1-µF or larger ceramic input bypass capacitor, connected between IN and GND and located close to the TPS794xx, is required for stability. It improves transient response, noise rejection, and ripple rejection. A higher-value input capacitor may be necessary if large, fast-rise-time load transients are anticipated or the device is located several inches from the power source.

Like most low dropout regulators, the TPS794xx requires an output capacitor connected between OUT and GND to stabilize the internal control loop. The minimum recommended capacitance is 2.2  $\mu$ F. Any 2.2  $\mu$ F or larger ceramic capacitor is suitable.

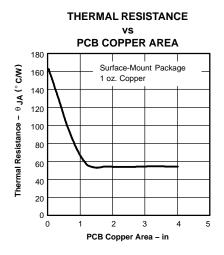
The internal voltage reference is a key source of noise in an LDO regulator. The TPS794xx has an NR pin which is connected to the voltage reference through a 250-k $\Omega$  internal resistor. The 250-k $\Omega$  internal resistor, in conjunction with an external bypass capacitor connected to the NR pin, creates a low-pass filter to reduce the voltage reference noise and, therefore, the noise at the regulator output. In order for the regulator to operate properly, the current flow out of the NR pin must be at a minimum, because any leakage current creates an IR drop across the internal resistor thus creating an output error. Therefore, the NR capacitor must have minimal leakage current. The bypass capacitor should be no more than 0.1  $\mu$ F to ensure that it is fully charged during the quickstart time provided by the internal switch shown in the functional block diagram.

For example, the TPS79428 exhibits only 32  $\mu V_{RMS}$  of output voltage noise using a 0.1- $\mu F$  ceramic NR capacitor and a 2.2- $\mu F$  ceramic output capacitor. Note that the output starts up slower as the bypass capacitance increases due to the RC time constant at the NR pin that is created by the internal 250- $k\Omega$  resistor and external capacitor.



#### **Board Layout Recommendation to Improve PSRR and Noise Performance**

To improve ac measurements like PSRR, output noise, and transient response, it is recommended that the board be designed with separate ground planes for  $V_{IN}$  and  $V_{OUT}$ , with each ground plane connected only at the ground pin of the device. In addition, the ground connection for the bypass capacitor should connect directly to the ground pin of the device.



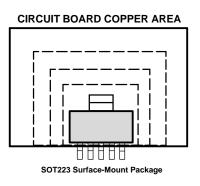


Figure 23. Thermal Resistance vs PCB Area for the SOT223-6.

#### **Power and Dissipation and Junction Temperature**

Specified regulator operation is assured to a junction temperature of  $125^{\circ}$ C; the maximum junction temperature should be restricted to  $125^{\circ}$ C under normal operating conditions. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation,  $P_{D(max)}$ , and the actual dissipation,  $P_D$ , which must be less than or equal to  $P_{D(max)}$ .

The maximum-power-dissipation limit is determined using the following equation:

$$P_{D(max)} = \frac{T_{J}max - T_{A}}{R_{\theta JA}}$$
(1)

#### where:

- T<sub>.I</sub>max is the maximum allowable junction temperature.
- $\bullet$   $R\theta_{JA}$  is the thermal resistence juntion-to-ambient for the package. See the power dissipation table and Figure 1
- T<sub>A</sub> is the ambient temperature.

The regulator dissipation is calculated using:

$$P_{D} = (V_{IN} - V_{OUT}) \times I_{OUT}$$
(2)

Power dissipation resulting from quiescent current is negligible. Excessive power dissipation triggers the thermal protection circuit.

#### **Regulator Mounting**

The tab of the SOT223-6 package is electrically connected to ground. For best thermal performance, the tab of the surface-mount version should be soldered directly to a circuit-board copper area. Increasing the copper area improves heat dissipation. Solder pad footprint recommendations for the devices are presented in an application bulletin *Solder Pad Recommendations for Surface-Mount Devices*, literature number AB-132, available from the TI web site (www.ti.com).



#### Programming the TPS79401 Adjustable LDO Regulator

The output voltage of the TPS79401 adjustable regulator is programmed using an external resistor divider as shown in Figure 24. The output voltage is calculated using:

$$V_{OUT} = V_{REF} \times \left(1 + \frac{R1}{R2}\right)$$
(3)

where:

V<sub>RFF</sub> = 1.2246 V typ (the internal reference voltage).

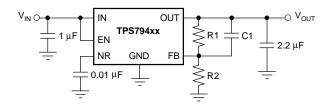
Resistors R1 and R2 should be chosen for approximately 40- $\mu$ A divider current. Lower value resistors can be used for improved noise performance, but the device wastes more power. Higher values should be avoided as leakage current at FB increases the output voltage error. The recommended design procedure is to choose R2 = 30.1 k $\Omega$  to set the divider current at 40  $\mu$ A, C1 = 15 pF for stability, and then calculate R1 using:

$$R1 = \left(\frac{V_{OUT}}{V_{REF}} - 1\right) \times R2 \tag{4}$$

In order to improve the stability of the adjustable version, it is suggested that a small compensation capacitor be placed between OUT and FB. For voltages < 1.8 V, the value of this capacitor should be 100 pF. For voltages > 1.8 V, the approximate value of this capacitor can be calculated as:

C1 = 
$$\frac{(3 \times 10^{-7}) \times (R1 + R2)}{(R1 \times R2)}$$
 (5)

The suggested value of this capacitor for several resistor ratios is shown in the table below. If this capacitor is not used (such as in a unity-gain configuration) or if an output voltage < 1.8 V is chosen, then the minimum recommended output capacitor is  $4.7 \, \mu F$  instead of  $2.2 \, \mu F$ .



# OUTPUT VOLTAGE PROGRAMMING GUIDE

OUTPUT VOLTAGE	R1	R2	C1	
2.5 V	31.6 kΩ	30.1 kΩ	22 pF	
3.3 V	49.9 kΩ	30.1 kΩ	15 pF	
3.6 V	59 kΩ	30.1 kΩ	15 pF	

Figure 24. TPS79401 Adjustable LDO Regulator Programming

#### **Regulator Protection**

The TPS794xx PMOS-pass transistor has a built-in back diode that conducts reverse current when the input voltage drops below the output voltage (e.g., during power-down). Current is conducted from the output to the input and is not internally limited. If extended reverse voltage operation is anticipated, external limiting might be appropriate.

The TPS794xx features internal current limiting and thermal protection. During normal operation, the TPS794xx limits output current to approximately 925 mA. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package or the absolute maximum voltage rating of the device. If the temperature of the device exceeds approximately 165°C, thermal-protection circuitry shuts it down. Once the device has cooled down to below approximately 140°C, regulator operation resumes.

<sup>&</sup>lt;sup>†</sup> Not Available on the DCQ package.

## THERMAL PAD MECHANICAL DATA



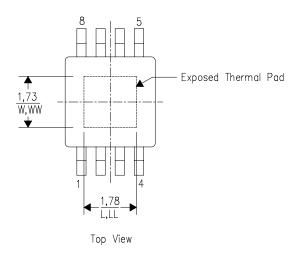
DGN (S-PDSO-G8)

#### THERMAL INFORMATION

This PowerPAD<sup>TM</sup> package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. When the thermal pad is soldered directly to the printed circuit board (PCB), the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to a ground plane or special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



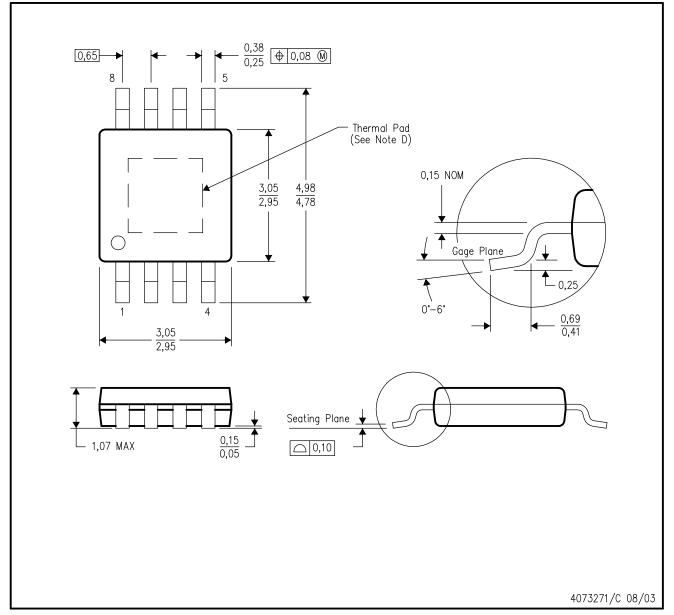
NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

4206323/- 12/04

# DGN (S-PDSO-G8)

## PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

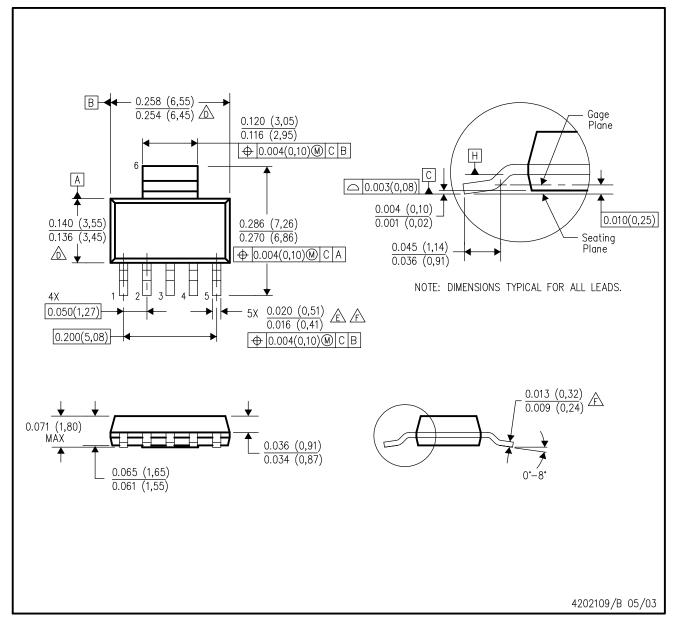
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion.
  - D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <a href="https://www.ti.com">https://www.ti.com</a>.
- E. Falls within JEDEC MO-187

PowerPAD is a trademark of Texas Instruments.



# DCQ (R-PDSO-G6)

## PLASTIC SMALL-OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Controlling dimension in inches.
- Body length and width dimensions are determined at the outermost extremes of the plastic body exclusive of mold flash, tie bar burrs, gate burrs, and interlead flash, but including any mismatch between the top and the bottom of the plastic body.
- Lead width dimension does not include dambar protrusion.
- Lead width and thickness dimensions apply to solder plated leads.
- G. Interlead flash allow 0.008 inch max.
- H. Gate burr/protrusion max. 0.006 inch.
- I. Datums A and B are to be determined at Datum H.
- J. Package dimensions per JEDEC outline drawing TO-261, issue B, dated Feb. 1999.
   This variation is not yet included.



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